stacking first and second semiconductor dies having substantially the same rectangular dimensions on top of one another;

mounting the first semiconductor die on a leadframe finger; and

mounting the second semiconductor die only on said first semiconductor die.

REMARKS

In paragraph 3 of the office action, the requirement is maintained that the Abstract be amended to define the spacer. The Examiner may recall that the spacer was an important element in a related case, but none of the claims now pending in this case have anything to do with a spacer. Therefore, reconsideration of the requirement to amend the Abstract is respectfully requested.

Claim 15 has been amended to call for a die mounted on a leadframe finger.

In Alagaratnam, the two dies are mounted on one another, but are clearly not mounted on the leadframe fingers to which they are connected by wire bonds. Instead, one of the dies is mounted on a leadframe paddle. Therefore, claim 15, as amended, patentably distinguishes over the cited reference.

For the same reason claims 15 and 32 are patentable.

In view of these remarks, the application is now in condition for allowance and the Examiner's prompt action in accordance therewith is respectfully requested.

Respectfully submitted,

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APPENDIX

15 (Twice Amended). A method for mounting multiple semiconductor dies on a single leadframe having fingers, comprising:

stacking at least two semiconductor dies having substantially the same rectangular dimensions on top of one another such that one of said dies is mounted on top of the leadframe fingers and the other of said dies is mounted on the die mounted on the leadframe fingers; and

wire bonding each of [the] said semiconductor dies to the leadframe.

Please amend claim 32 as follows:

32 (Amended). A method for mounting multiple semiconductor dies on a single leadframe having fingers, comprising:

stacking first and second semiconductor dies having substantially the same rectangular dimensions on top of one another;

mounting the first semiconductor die on a leadframe finger; and

mounting the second semiconductor die only on said first semiconductor die.